



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silk	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste	Not specified	0 mm	White	1	0
F.Mask	Top Solder Mask	Not specified	0.015 mm	Black	3.3	0
F.Cu	copper	Not specified	0.048 mm	Black	1	0
Dielectric 1	prepreg	FR4-TG150	0.109 mm	FR4 natural	4.2	0.02
In1.Cu	copper	Not specified	0.036 mm	Black	1	0
Dielectric 2	core	FR4-TG150	1.194 mm	FR4 natural	4.2	0.02
In2.Cu	copper	Not specified	0.036 mm	Black	1	0
Dielectric 3	prepreg	FR4-TG150	0.109 mm	FR4 natural	4.2	0.02
B.Cu	copper	Not specified	0.048 mm	Black	1	0
B.Mask	Bottom Solder Mask	Not specified	0.015 mm	Black	3.3	0
B.Paste	Bottom Solder Paste	Not specified	0 mm	White	1	0
B.Silk	Bottom Silk Screen	Not specified	0 mm	White	1	0

IMPEDANCE CONTROL TABLE					
LAYER	TRACE [MM]	SPACING [MM]	IMPEDANCE SINGLE-ENDED	IMPEDANCE DIFFERENTIAL	TOLERANCE
B.Cu	0.178	0.127	NA	90 ohm	+/- 10%
F.Cu	0.178	0.127	NA	90 ohm	+/- 10%

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6100 mm
Board overall dimensions:	50.8000 mm x 103.0000 mm	Min hole diameter:	0.2000 mm
Min track/spacing:	0.2000 mm / 0.1500 mm	Impedance Control:	Yes
Copper Finish:	ENIG	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		

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Sheet:  
File: Notecarrier-F.kicad\_pcb

Title: Notecarrier-F

Size: A4 Date: 2023-05-03  
KiCad E.D.A. kicad 7.0.2-0

Rev: A  
Id: 1/1